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TECHNICAL REPORT

EMC IC modelling -
Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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CONTENTS

FOREWORD 3
1 Scope 5
2 Normative references 5
3 Terms, definitions and abbreviations 5
  3.1 Terms and definitions 5
  3.2 Abbreviated terms 6
4 Philosophy 7
5 ICIM-CI model extraction flow 7
  5.1 General 7
  5.2 Failure criteria definition 9
  5.3 PDN extraction 10
    5.3.1 General 10
    5.3.2 PDN extraction from SYZ-parameters measurements 11
    5.3.3 PDN extraction from existing models 13
    5.3.4 PDN extraction from package geometry import and simulation model generator 14
  5.4 Conducted immunity characterization 15
  5.5 IB extraction 18
  5.6 Validation of the ICIM-CI model 23
  5.7 Final ICIM-CI model 24
6 Use of ICIM-CI model for immunity prediction on an application PCB 25
  6.1 General 25
  6.2 Calculation of the power flowing into the under-test IC pin 26
Annex A (informative) Example of ICIM-CI model written as SPICE subckt 29
  A.1 General 29
  A.2 Example 29
Annex B (informative) Example of conducted immunity calculation applied to a LIN transceiver used in an automotive application 33
  B.1 General 33
  B.2 LIN driver ICIM-CI model 33
  B.3 Application board modelling 34
  B.4 Conducted immunity calculation 36
    B.4.1 Calculation without non-linear element 36
    B.4.2 Calculation with non-linear element 37
Bibliography 39

Figure 1 – Example of ICIM-CI model structure 8
Figure 2 – ICIM-CI model extraction flow proposal 8
Figure 3 – Pin description of the IC under test 9
Figure 4 – Example of PCB dedicated to S-parameters measurement 11
Figure 5 – Example of reflection coefficient measurement performed on the IC under test 12
Figure 6 – Example of LIN pin impedances depending on state 12
Figure 7 – Example of transmission coefficient measurement performed on the IC under test 13
Figure 8 – Structure of IBIS model 14

Figure 9 – Example of packaging extraction tool ... 14
Figure 10 – Example of parasitic elements computation with an advanced packaging extraction tool ... 15
Figure 11 – Example of DPI test setup ... 15
Figure 12 – Example of PCB dedicated to DPI test ... 16
Figure 13 – Example of a configuration for LIN driver DPI measurement ... 17
Figure 14 – Example of incident power at IB extraction board LIN input during DPI measurement of the initial configuration for each OO ... 17
Figure 15 – Example of block diagram for DPI setup modelling ... 19
Figure 16 – Example of DPI SPICE modelling to calculated power transmitted to VBAT pin during a 0 dBm power injection at IB extraction board input ... 20
Figure 17 – Example of IB extraction board trace modelling using SPICE subcircuit model ... 20
Figure 18 – Example of transmitted power and voltage magnitude calculated at VBAT pin of the IC under test during DPI SPICE simulation performed at 0 dBm ... 21
Figure 19 – Example of comparison incident vs transmitted power for a DPI on + 12 V board pin ... 22
Figure 20 – Example of transmitted power calculated at LIN pin input during DPI SPICE simulation performed at 0 dBm: validation vs IB extraction configuration ... 23
Figure 21 – Example of incident power calculated at LIN pin input inducing a fault on LIN pin during DPI SPICE validation simulation: calculation vs measurement ... 24
Figure 22 – ICIM-CI XML writer ... 25
Figure 23 – Example of white box construction of a DPI setup modelling at application level ... 26
Figure 24 – Example of transmitted power calculation at application board ... 27
Figure 25 – Example of voltage V and current I calculation ... 27
Figure 26 – Example of fault prediction ... 28
Figure A.1 – Example of ICIM-CI model written as SPICE subcircuit ... 32
Figure B.1 – Example of an automotive application board ... 33
Figure B.2 – LIN driver ICIM-CI model ... 34
Figure B.3 – Example of an automotive application board schematic ... 35
Figure B.4 – Example of an automotive application board 3D modelling ... 35
Figure B.5 – Example of conducted immunity calculation modelling ... 36
Figure B.6 – Example of comparison of the calculated transmitted power with the IB and the RF power injection measurement – without non-linear element- ... 37
Figure B.7 – Example of comparison of the calculated transmitted power with the IB and the RF power injection measurement – with non-linear elements- ... 37
Figure B.8 – Example of current and voltage calculation during a transient analysis ... 38
Figure B.9 – Example of calculated current and voltage at 10 MHz (Nyquist sampling) ... 38

Table 1 – Examples of OO, failure criteria and DI for different types of IC ... 9
Table 2 – Examples of OO, failure criteria and DI for the IC under test ... 10
Table B.1 – OO, failure criteria and DI for the LIN transceiver under test ... 34

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EMC IC modelling - Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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1 Scope

This part of IEC 62433-4 provides an overview of good practices to extract an ICIM-CI model from measurements and to build a numerical model of the PCB in which the ICIM-CI model is used to predict RF immunity of an IC in its application PCB.

This document also discusses factors which can be considered to obtain proper results in an ICIM-CI model extraction and use of the actual model at the PCB level.

2 Normative references

There are no normative references in this document.